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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Application Serial No. .... 09/148,723  
Filing Date .... September 3, 1998  
Inventor .... Warren M. Farnworth et al.  
Assignee .... Micron Technology, Inc.  
Group Art Unit .... 3729  
Examiner .... D. Tugbang  
Attorney's Docket No. .... MI22-981  
Title: Methods of Bonding Solder Balls To Bond Pads on a Substrate

**SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT**

**References -- See Attached Form PTO-1449**

This Request for Continued Examination (RCE) Application is being filed in an abundance of caution to ensure consideration of the references listed on the attached form PTO-1449.

The attached form PTO-1449 is submitted in compliance with 37 CFR §1.56. No admission is made regarding whether the submitted references are prior art.

Respectfully submitted,

Date: 4-28-03

D. Brent Kenady  
Reg. No. 40,045  
Wells St. John P.S.  
601 W. First Avenue, Suite 1300  
Spokane, WA 99201-3828  
(509) 624-4276

TECHNOLOGY CENTER R3700

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